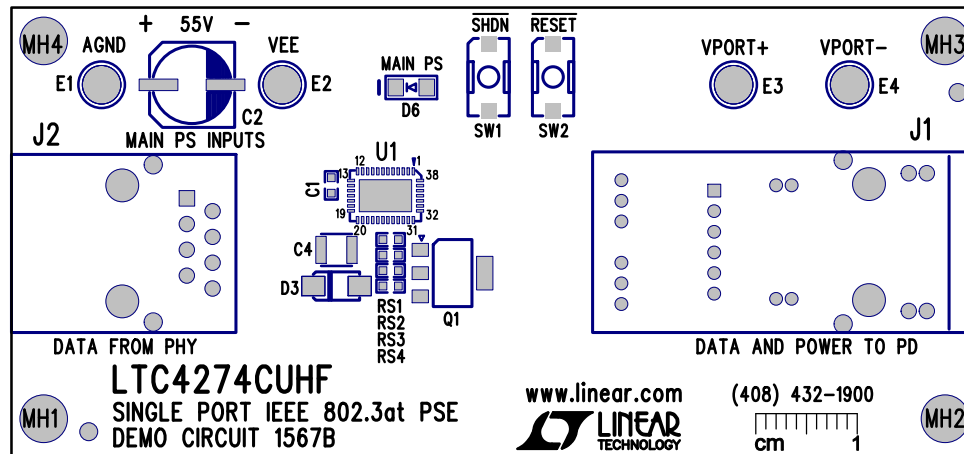
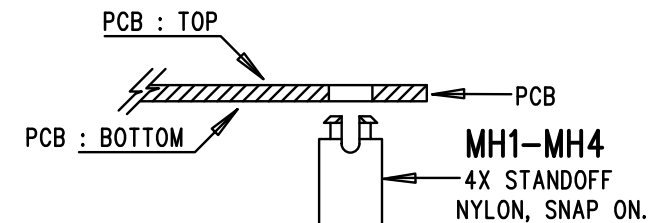



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	REBUILD WITH CHANGE	DILIAN R.	07-09-15



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. NO SHUNT.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN BELOW:



APPROVALS		 <div> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY </div>		
PCB DES.	KIM T.			
APP ENG.	DILIAN R.			
		TITLE: TOP ASSEMBLY DRAWING		
		SINGLE PORT IEEE 802.3at PSE		
		SIZE N/A	IC NO. LTC4274CUHF DEMO CIRCUIT 1567B	REV. 2
SCALE = NONE		FILENAME: DC1567B-2.PCB		SHT 1 OF 2